

# ASML 2500/40 ACCEPTANCE TEST SPECIFICATIONS

<b>Customer:</b>	EO Technical
<b>Site:</b>	Vancouver, Wa
<b>Machine serial number:</b>	765
<b>Model:</b>	2500/40
<b>Wafer size:</b>	6"
<b>Purchase order no:</b>	
<b>Software Release:</b>	8.1.0
<b>Test completion date:</b>	<i>See notes in side-bar</i>

Parameter	Specification (absolute values)	FAT		SAT	
		Measured	Accept	Measured	Accept
<b>1. Illumination</b>					
1.1 Illumination Homogeneity					
15.0 x 15.0 mm [%]	≤ 3.0	2.86	7/28/2022		
9.4 x 19.0 mm [%]	≤ 3.0	2.43	7/28/2022		
Illumination intensity [mW/cm <sup>2</sup> ]	>280	324	7/28/2022		
<b>2. Reticle masking</b>					
2.1 Reticle masking [μm]	≤ 500	200	7/29/2022		
<b>3. Lens distortion</b>					
3.1 Non-correctable error [nm]					
X @15x15(nm)	≤ 120	137	8/15/2022		
Y @15x15(nm)	≤ 120	166	8/15/2022		
Mag(nm/cm)	<50	-48	8/15/2022		
Die Rotation(urad)	<5	0.476	8/15/2022		
Trapezoidal X(nm/cm <sup>2</sup> )	<50	-32	8/15/2022		
Trapezoidal Y(nm/cm <sup>2</sup> )	<50	-24	8/15/2022		
<b>4. Material handling</b>					
4.1 Pre-alignment accuracy(Optical Sensor)					
Xm1w1 (um)	≤ 7	2.3	7/28/2022		
Ym1w1 (um)	≤ 7	3.3	7/28/2022		

Ym1w2 (um)	≤ 7	2.3	7/28/2022		
<b>5. Overlay performance</b>					
5.1 Stage repeatability					
X [nm]	≤ 100	17.3	8/15/2022		
Y [nm]	≤ 100	58.7	8/18/2022		
5.2 Single machine overlay (99.7%)					
X - Max 99.7%	≤ 150	57	8/15/2022		
Y - Max 99.7%	≤ 150	57	8/15/2022		
<b>6. Wafer throughput</b>					
6.1 Wafer throughput at 200 mJ/cm <sup>2</sup>	≥ 64	64.75	8/15/2022		
6.4 Reticle exchange time (seconds)	≤ 40	24.3	7/28/2022		

<b>The tests below require CD CIM or Other</b>					
Focus Leveling					
Out Of Focus	Zero per wafer				
Imaging (Target CD)					
UDOF	>1.2um				
Intra Filed CD	+/- 0.05um @ 0.5+/-0.025um mean CD				
Target CD reproducibility	0.5 +/-0.05um				
Overlay					
Box in Box	<150nm				
Overlay on Product wafer	<150nm				
System Stability					
3 day run test	Zero errors				
Contamination					
Topside particles	,3 Particles (0.5um or larger)				